

Tech-X Corporation invites you to visit us in Booth #119 at the [AVS 57<sup>th</sup> International Symposium and Exhibition](#), October 17 - 22, in Albuquerque.

We are proud to present the latest release of our electromagnetic plasma simulation software, [VORPAL](http://vorpal.txcorp.com) (<http://vorpal.txcorp.com>). VORPAL 4.2 includes improved documentation, simplified installation on all platforms, additional collision models, import of user-defined secondary electron yield data, a new photoemission model, delta-F particles for modeling tokamak geometries, and new field updaters.

Stop by our booth to see a demonstration of any of these new features of VORPAL 4.2. Our staff will be happy to discuss the details of how VORPAL might fit your modeling needs.

Personnel from Tech-X will present the following poster:

**PS-TuP16 Numerical Simulations of a Magnetron Plasma Sputtering System using VORPAL**, *C.M. Roark, C. Zhou, P.H. Stoltz*, Tech-X Corporation, during the Plasma Science and Technology Poster Session, Tuesday afternoon in the Southwest Exhibit Hall from 6:00 PM - 8:00 PM